



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-07-24
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDRF CHAMPION	Representative title	MDRFMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement
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Legal statement			
Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM8AF6268TCX	JE5B*79BX141	A	0959	2025-07-24
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	176	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	7x7	48	Gull wing	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			false
Exemption Id.	Description		
,			

QueryList : REACH-21st January 2025				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	JE5B*79BX141		176.356		6000000	1000000
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	4.521	mg	supplier	die	Silicon(Si)	7440-21-3		4.364	mg	965273	24745
				supplier	metallization	Aluminium(Al)	7429-90-5		0.012	mg	2654	68
				supplier	metallization	Copper(Cu)	7440-50-8		0.040	mg	8848	227
				supplier	metallization	Titanium(Ti)	7440-32-6		0.003	mg	664	17
				supplier	Passivation	Silicon Oxide	7631-86-9		0.065	mg	14377	369
Leadframe (C7025)	M-011 Other inorganic materials	74.402	mg	supplier	Polymer coating	PIX1 Polyimide AP2210A / HD8820 - Gamma-but	96-48-0		0.037	mg	8184	210
				supplier	alloy	Copper (Cu)	7440-50-8		71.787	mg	964855	407055
				supplier	alloy	Nickel (Ni)	7440-02-0		2.064	mg	27746	11706
				supplier	alloy	Silicium (Si)	7440-21-3		0.447	mg	6012	2536
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.103	mg	1387	585
Leadframe Coating (NiPdAu)	M-011 Other inorganic materials	0.405	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.371	mg	914840	2104
				supplier	coating	Palladium (Pd)	7440-05-3		0.012	mg	29660	68
				supplier	coating	Gold (Au)	7440-57-5		0.011	mg	27750	63
Glue epoxy (EN4900)	M-011 Other inorganic materials	1.954	mg	supplier	coating	Silver (Ag)	7440-22-4		0.011	mg	27750	63
				supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.505	mg	770000	8532
				supplier	glue or soft solder	Epoxy Cresol Novolak	29690-82-2		0.442	mg	226000	2504
Bonding wire (Au)	M-011 Other inorganic materials	0.913	mg	supplier	glue or soft solder	1-isopropyl-2,2-dimethyltrimethylene diisobutyrat	6846-50-0		0.008	mg	4000	44
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.913	mg	1000000	5178
Encapsulation (EME-G700LS)	M-011 Other inorganic materials	94.161	mg	supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		6.786	mg	72069	38479
				supplier	Moulding Compound	Phenol Resin	Proprietary		4.847	mg	51478	27485
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		82.043	mg	871305	465211
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.485	mg	5148	2749